



3D Packaging & Integration North America TC Chapter

NA Standards Summer Meeting 2024

Monday, July 15

Online via Official Virtual Technical Committee Chapter Meeting (OVTCCM)

13:00–14:30 Pacific

AGENDA

	Time
1 Welcome/Call to Order	13:00
1.1 Please log into www.svm.semi.org for voting	
1.2 Required Elements (Membership Requirements, Antitrust and Intellectual Property Reminders, and Effective Meeting Guidelines)	
1.3 Introductions	
1.4 Agenda Review	
2 Liaison Reports	13:15
2.1 Japan TC Chapter	
2.2 Taiwan TC Chapter	
3 Staff Report	13:25
4 Review of Previous Meeting Minutes	13:30
5 Ballot Review	13:35
5.1 Document 7100 — Revision to SEMI 3D4-0915 (Reapproved 0222), Guide for Metrology for Measuring Thickness, Total Thickness Variation (TTV), Bow, Warp/Sori, and Flatness of Bonded Wafer Stacks	
6 Task Force Updates	14:00
6.1 3DP&I Bonded Wafer Stacks and Inspection & Metrology Task Forces	
6.2 Panel Level Packaging (PLP) Panel Task Force (<i>did not meet</i>)	



	Time
7 Old Business	14:10
7.1 Five-Year Review	
- SEMI 3D1-0519, Terminology for Through Silicon via Geometrical Metrology - SEMI 3D21-1019, Guide for Describing Glass-Based Material for Use in 3DS-IC Process - SEMI 3D22-1219, Guide on Measurements of Openings and Vias in Glass - SEMI 3D11-1214 (Reapproved 0420), Terminology for Through Glass Via and Blind Via in Glass Geometrical Metrology - SEMI 3D10-0814 (Reapproved 0420), Guide to Describing Materials Properties for Intermediate Wafers for Use in a 300 mm 3DS-IC Wafer Stack - SEMI 3D9-0914 (Reapproved 0420), Guide for Describing Materials Properties for a 300 mm 3DS-IC Wafer Stack	
8 New Business	14:20
9 Action Item Review	14:25
10 Next Meeting and Adjournment	14:30
10.1 The next meeting is tentatively scheduled for the week of November 4-7, in conjunction with NA Standards Fall Meetings 2024. Schedule details TBD. Please check www.semi.org/standards for updates.	

Tentative Schedule:

- Thursday, November 7
 - TBD**, Panel Level Packaging (PLP) Panel TF
 - 11:00-12:00, Joint 3DP&I Bonded Wafer Stacks Task Force, and 3DP&I Inspection & Metrology Task Force
 - 13:00-14:30, 3DP&I NA TC Chapter

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NOTE:

Standards meetings are open to all, but you must be a SEMI Standards Program Member to attend.

If you are not a member, please register for the International SEMI Standards Program here:
<https://www.semi.org/standardsmembership>

STANDARDS VIRTUAL MEETING INFORMATION:

Please email Laura Nguyen, Lnguyen@semi.org, for teleconference information.